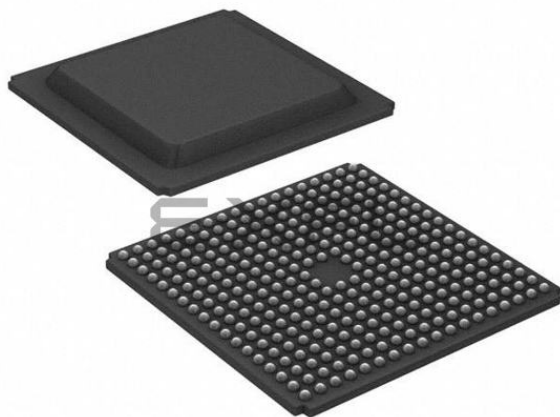




Welcome to [E-XFL.COM](https://www.e-xfl.com)

Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Active
Number of LABs/CLBs	3328
Number of Logic Elements/Cells	29952
Total RAM Bits	589824
Number of I/O	221
Number of Gates	1500000
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	320-BGA
Supplier Device Package	320-FBGA (19x19)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc3s1500-4fg320i

IOBs

For additional information, refer to the chapter entitled “Using I/O Resources” in [UG331: Spartan-3 Generation FPGA User Guide](#).

IOB Overview

The Input/Output Block (IOB) provides a programmable, bidirectional interface between an I/O pin and the FPGA's internal logic.

A simplified diagram of the IOB's internal structure appears in [Figure 7](#). There are three main signal paths within the IOB: the output path, input path, and 3-state path. Each path has its own pair of storage elements that can act as either registers or latches. For more information, see the [Storage Element Functions](#) section. The three main signal paths are as follows:

- The input path carries data from the pad, which is bonded to a package pin, through an optional programmable delay element directly to the I line. There are alternate routes through a pair of storage elements to the IQ1 and IQ2 lines. The IOB outputs I, IQ1, and IQ2 all lead to the FPGA's internal logic. The delay element can be set to ensure a hold time of zero.
- The output path, starting with the O1 and O2 lines, carries data from the FPGA's internal logic through a multiplexer and then a three-state driver to the IOB pad. In addition to this direct path, the multiplexer provides the option to insert a pair of storage elements.
- The 3-state path determines when the output driver is high impedance. The T1 and T2 lines carry data from the FPGA's internal logic through a multiplexer to the output driver. In addition to this direct path, the multiplexer provides the option to insert a pair of storage elements. When the T1 or T2 lines are asserted High, the output driver is high-impedance (floating, hi-Z). The output driver is active-Low enabled.
- All signal paths entering the IOB, including those associated with the storage elements, have an inverter option. Any inverter placed on these paths is automatically absorbed into the IOB.

Storage Element Functions

There are three pairs of storage elements in each IOB, one pair for each of the three paths. It is possible to configure each of these storage elements as an edge-triggered D-type flip-flop (FD) or a level-sensitive latch (LD).

The storage-element-pair on either the Output path or the Three-State path can be used together with a special multiplexer to produce Double-Data-Rate (DDR) transmission. This is accomplished by taking data synchronized to the clock signal's rising edge and converting them to bits synchronized on both the rising and the falling edge. The combination of two registers and a multiplexer is referred to as a Double-Data-Rate D-type flip-flop (FDDR). See [Double-Data-Rate Transmission, page 12](#) for more information.

The signal paths associated with the storage element are described in [Table 5](#).

Table 5: Storage Element Signal Description

Storage Element Signal	Description	Function
D	Data input	Data at this input is stored on the active edge of CK enabled by CE. For latch operation when the input is enabled, data passes directly to the output Q.
Q	Data output	The data on this output reflects the state of the storage element. For operation as a latch in transparent mode, Q will mirror the data at D.
CK	Clock input	A signal's active edge on this input with CE asserted, loads data into the storage element.
CE	Clock Enable input	When asserted, this input enables CK. If not connected, CE defaults to the asserted state.
SR	Set/Reset	Forces storage element into the state specified by the SRHIGH/SRLOW attributes. The SYNC/ASYNC attribute setting determines if the SR input is synchronized to the clock or not.
REV	Reverse	Used together with SR. Forces storage element into the state opposite from what SR does.

DFS Clock Output Connections

There are two basic cases that determine how to connect the DFS clock outputs: on-chip and off-chip, which are illustrated in sections [a] and [c], respectively, of [Figure 21](#). This is similar to what has already been described for the DLL component. See [DLL Clock Output and Feedback Connections, page 34](#).

In the on-chip case, it is possible to connect either of the DFS's two output clock signals through general routing resources to the FPGA's internal registers. Either a Global Clock Buffer (BUFG) or a BUFGMUX affords access to the global clock network. The optional feedback loop is formed in this way, routing CLK0 to a global clock net, which in turn drives the CLKFB input.

In the off-chip case, the DFS's two output clock signals, plus CLK0 for an optional feedback loop, can exit the FPGA using output buffers (OBUF) to drive a clock network plus registers on the board. The feedback loop is formed by feeding the CLK0 signal back into the FPGA using an IBUFG, which directly accesses the global clock network, or an IBUF. Then, the global clock net is connected directly to the CLKFB input.

Phase Shifter (PS)

The DCM provides two approaches to controlling the phase of a DCM clock output signal relative to the CLKIN signal: First, there are nine clock outputs that employ the DLL to achieve a desired phase relationship: CLK0, CLK90, CLK180, CLK270, CLK2X, CLK2X180, CLKDV CLKFX, and CLKFX180. These outputs afford "coarse" phase control.

The second approach uses the PS component described in this section to provide a still finer degree of control. The PS component is only available when the DLL is operating in its low-frequency mode. The PS component phase shifts the DCM output clocks by introducing a "fine phase shift" (T_{PS}) between the CLKFB and CLKIN signals inside the DLL component. The user can control this fine phase shift down to a resolution of 1/256 of a CLKIN cycle or one tap delay (DCM_TAP), whichever is greater. When in use, the PS component shifts the phase of all nine DCM clock output signals together. If the PS component is used together with a DCM clock output such as the CLK90, CLK180, CLK270, CLK2X180 and CLKFX180, then the fine phase shift of the former gets added to the coarse phase shift of the latter.

PS Component Enabling and Mode Selection

The CLKOUT_PHASE_SHIFT attribute enables the PS component for use in addition to selecting between two operating modes. As described in [Table 20](#), this attribute has three possible values: NONE, FIXED and VARIABLE. When CLKOUT_PHASE_SHIFT is set to NONE, the PS component is disabled and its inputs, PSEN, PSCLK, and PSINCDEC, must be tied to GND. The set of waveforms in section [a] of [Figure 22](#) shows the disabled case, where the DLL maintains a zero-phase alignment of signals CLKFB and CLKIN upon which the PS component has no effect. The PS component is enabled by setting the attribute to either the FIXED or VARIABLE values, which select the Fixed Phase mode and the Variable Phase mode, respectively. These two modes are described in the sections that follow

Determining the Fine Phase Shift

The user controls the phase shift of CLKFB relative to CLKIN by setting and/or adjusting the value of the PHASE_SHIFT attribute. This value must be an integer ranging from -255 to +255. The PS component uses this value to calculate the desired fine phase shift (T_{PS}) as a fraction of the CLKIN period (T_{CLKIN}). Given values for PHASE-SHIFT and T_{CLKIN} , it is possible to calculate T_{PS} as follows:

$$T_{PS} = T_{CLKIN}(\text{PHASE_SHIFT}/256) \quad \text{Equation 4}$$

Both the Fixed Phase and Variable Phase operating modes employ this calculation. If the PHASE_SHIFT value is zero, then CLKFB and CLKIN will be in phase, the same as when the PS component is disabled. When the PHASE_SHIFT value is positive, the CLKFB signal will be shifted later in time with respect to CLKIN. If the attribute value is negative, the CLKFB signal will be shifted earlier in time with respect to CLKIN.

The Fixed Phase Mode

This mode fixes the desired fine phase shift to a fraction of the T_{CLKIN} , as determined by [Equation 4](#) and its user-selected PHASE_SHIFT value P. The set of waveforms in section [b] of [Figure 22](#) illustrates the relationship between CLKFB and CLKIN in the Fixed Phase mode. In the Fixed Phase mode, the PSEN, PSCLK and PSINCDEC inputs are not used and must be tied to GND. Fixed phase shift requires ISE software version 10.1.03 or later.

Each BUFGMUX element, shown in [Figure 24](#), is a 2-to-1 multiplexer that can receive signals from any of the four following sources:

- One of the four Global Clock inputs on the same side of the die—top or bottom—as the BUFGMUX element in use.
- Any of four nearby horizontal Double lines.
- Any of four outputs from the DCM in the right-hand quadrant that is on the same side of the die as the BUFGMUX element in use.
- Any of four outputs from the DCM in the left-hand quadrant that is on the same side of the die as the BUFGMUX element in use.

The multiplexer select line, S, chooses which of the two inputs, I0 or I1, drives the BUFGMUX's output signal, O, as described in [Table 25](#). The switching from one clock to the other is glitchless, and done in such a way that the output High and Low times are never shorter than the shortest High or Low time of either input clock.

Table 25: BUFGMUX Select Mechanism

S Input	O Output
0	I0 Input
1	I1 Input

The two clock inputs can be asynchronous with regard to each other, and the S input can change at any time, except for a short setup time prior to the rising edge of the presently selected clock (I0 or I1). Violating this setup time requirement can result in an undefined runt pulse output.

The BUFG clock buffer primitive drives a single clock signal onto the clock network and is essentially the same element as a BUFGMUX, just without the clock select mechanism. Similarly, the BUFGCE primitive creates an enabled clock buffer using the BUFGMUX select mechanism.

Each BUFGMUX buffers incoming clock signals to two possible destinations:

- The vertical spine belonging to the same side of the die—top or bottom—as the BUFGMUX element in use. The two spines—top and bottom—each comprise four vertical clock lines, each running from one of the BUFGMUX elements on the same side towards the center of the die. At the center of the die, clock signals reach the eight-line horizontal spine, which spans the width of the die. In turn, the horizontal spine branches out into a subsidiary clock interconnect that accesses the CLBs.
- The clock input of either DCM on the same side of the die—top or bottom—as the BUFGMUX element in use.

Use either a BUFGMUX element or a BUFG (Global Clock Buffer) element to place a Global input in the design. For the purpose of minimizing the dynamic power dissipation of the clock network, the Xilinx development software automatically disables all clock line segments that a design does not use.

A global clock line ideally drives clock inputs on the various clocked elements within the FPGA, such as CLB or IOB flip-flops or block RAMs. A global clock line also optionally drives combinatorial inputs. However, doing so provides additional loading on the clock line that might also affect clock jitter. Ideally, drive combinatorial inputs using the signal that also drives the input to the BUFGMUX or BUFG element.

For more details, refer to the chapter entitled “Using Global Clock Resources” in [UG331](#).

Table 33: General DC Characteristics of User I/O, Dual-Purpose, and Dedicated Pins

Symbol	Description	Test Conditions	Min	Typ	Max	Units
$I_L^{(2)(4)}$	Leakage current at User I/O, Dual-Purpose, and Dedicated pins	Driver is Hi-Z, $V_{IN} = 0V$ or V_{CCO} max, sample-tested	$V_{CCO} \geq 3.0V$	—	—	± 25 μA
			$V_{CCO} < 3.0V$	—	—	± 10 μA
$I_{RPU}^{(3)}$	Current through pull-up resistor at User I/O, Dual-Purpose, and Dedicated pins	$V_{IN} = 0V$, $V_{CCO} = 3.3V$	—0.84	—	—2.35	mA
		$V_{IN} = 0V$, $V_{CCO} = 3.0V$	—0.69	—	—1.99	mA
		$V_{IN} = 0V$, $V_{CCO} = 2.5V$	—0.47	—	—1.41	mA
		$V_{IN} = 0V$, $V_{CCO} = 1.8V$	—0.21	—	—0.69	mA
		$V_{IN} = 0V$, $V_{CCO} = 1.5V$	—0.13	—	—0.43	mA
		$V_{IN} = 0V$, $V_{CCO} = 1.2V$	—0.06	—	—0.22	mA
$R_{PU}^{(3)}$	Equivalent resistance of pull-up resistor at User I/O, Dual-Purpose, and Dedicated pins, derived from I_{RPU}	$V_{CCO} = 3.0V$ to $3.465V$	1.27	—	4.11	k Ω
		$V_{CCO} = 2.3V$ to $2.7V$	1.15	—	3.25	k Ω
		$V_{CCO} = 1.7V$ to $1.9V$	2.45	—	9.10	k Ω
		$V_{CCO} = 1.4V$ to $1.6V$	3.25	—	12.10	k Ω
		$V_{CCO} = 1.14$ to $1.26V$	5.15	—	21.00	k Ω
$I_{RPD}^{(3)}$	Current through pull-down resistor at User I/O, Dual-Purpose, and Dedicated pins	$V_{IN} = V_{CCO}$	0.37	—	1.67	mA
$R_{PD}^{(3)}$	Equivalent resistance of pull-down resistor at User I/O, Dual-Purpose, and Dedicated pins, driven from I_{RPD}	$V_{IN} = V_{CCO} = 3.0V$ to $3.465V$	1.75	—	9.35	k Ω
		$V_{IN} = V_{CCO} = 2.3V$ to $2.7V$	1.35	—	7.30	k Ω
		$V_{IN} = V_{CCO} = 1.7V$ to $1.9V$	1.00	—	5.15	k Ω
		$V_{IN} = V_{CCO} = 1.4V$ to $1.6V$	0.85	—	4.35	k Ω
		$V_{IN} = V_{CCO} = 1.14$ to $1.26V$	0.68	—	3.465	k Ω
R_{DCI}	Value of external reference resistor to support DCI I/O standards		20	—	100	Ω
I_{REF}	V_{REF} current per pin	$V_{CCO} \geq 3.0V$	—	—	± 25	μA
		$V_{CCO} < 3.0V$	—	—	± 10	μA
C_{IN}	Input capacitance		3	—	10	pF

Notes:

- The numbers in this table are based on the conditions set forth in [Table 32](#).
- The I_L specification applies to every I/O pin throughout power-on as long as the voltage on that pin stays between the absolute V_{IN} minimum and maximum values ([Table 28](#)). For hot-swap applications, at the time of card connection, be sure to keep all I/O voltages within this range before applying V_{CCO} power. Consider applying V_{CCO} power before connecting the signal lines, to avoid turning on the ESD protection diodes, shown in Module 2: [Figure 7, page 11](#). When the FPGA is completely unpowered, the I/O pins are high impedance, but there is a path through the upper and lower ESD protection diodes.
- This parameter is based on characterization. The pull-up resistance $R_{PU} = V_{CCO} / I_{RPU}$. The pull-down resistance $R_{PD} = V_{IN} / I_{RPD}$. Spartan-3 family values for both resistances are stronger than they have been for previous FPGA families.
- For single-ended signals that are placed on a differential-capable I/O, V_{IN} of $-0.2V$ to $-0.3V$ is supported but can cause increased leakage between the two pins. See the *Parasitic Leakage* section in [UG331, Spartan-3 Generation FPGA User Guide](#).

Table 47: Output Timing Adjustments for IOB (Cont'd)

Convert Output Time from LVCMOS25 with 12mA Drive and Fast Slew Rate to the Following Signal Standard (IOSTANDARD)			Add the Adjustment Below		Units
			Speed Grade		
			-5	-4	
LVCMOS18	Slow	2 mA	5.49	6.31	ns
		4 mA	3.45	3.97	ns
		6 mA	2.84	3.26	ns
		8 mA	2.62	3.01	ns
		12 mA	2.11	2.43	ns
		16 mA	2.07	2.38	ns
	Fast	2 mA	2.50	2.88	ns
		4 mA	1.15	1.32	ns
		6 mA	0.96	1.10	ns
		8 mA	0.87	1.01	ns
		12 mA	0.79	0.91	ns
		16 mA	0.76	0.87	ns
LVDCI_18			0.81	0.94	ns
LVDCI_DV2_18			0.67	0.77	ns
LVCMOS25	Slow	2 mA	6.43	7.39	ns
		4 mA	4.15	4.77	ns
		6 mA	3.38	3.89	ns
		8 mA	2.99	3.44	ns
		12 mA	2.53	2.91	ns
		16 mA	2.50	2.87	ns
		24 mA	2.22	2.55	ns
	Fast	2 mA	3.27	3.76	ns
		4 mA	1.87	2.15	ns
		6 mA	0.32	0.37	ns
		8 mA	0.19	0.22	ns
		12 mA	0	0	ns
		16 mA	−0.02	−0.01	ns
		24 mA	−0.04	−0.02	ns
LVDCI_25			0.27	0.31	ns
LVDCI_DV2_25			0.16	0.19	ns

Table 59: Switching Characteristics for the DLL (Cont'd)

Symbol	Description	Frequency Mode / FCLKIN Range	Device	Speed Grade				Units	
				-5		-4			
				Min	Max	Min	Max		
Lock Time									
LOCK_DLL	When using the DLL alone: The time from deassertion at the DCM's Reset input to the rising transition at its LOCKED output. When the DCM is locked, the CLKIN and CLKFB signals are in phase	$18\text{ MHz} \leq F_{\text{CLKIN}} \leq 30\text{ MHz}$	All	—	2.88	—	2.88	ms	
		$30\text{ MHz} < F_{\text{CLKIN}} \leq 40\text{ MHz}$		—	2.16	—	2.16	ms	
		$40\text{ MHz} < F_{\text{CLKIN}} \leq 50\text{ MHz}$		—	1.20	—	1.20	ms	
		$50\text{ MHz} < F_{\text{CLKIN}} \leq 60\text{ MHz}$		—	0.60	—	0.60	ms	
		$F_{\text{CLKIN}} > 60\text{ MHz}$		—	0.48	—	0.48	ms	
Delay Lines									
DCM_TAP	Delay tap resolution	All	All	30.0	60.0	30.0	60.0	ps	

Notes:

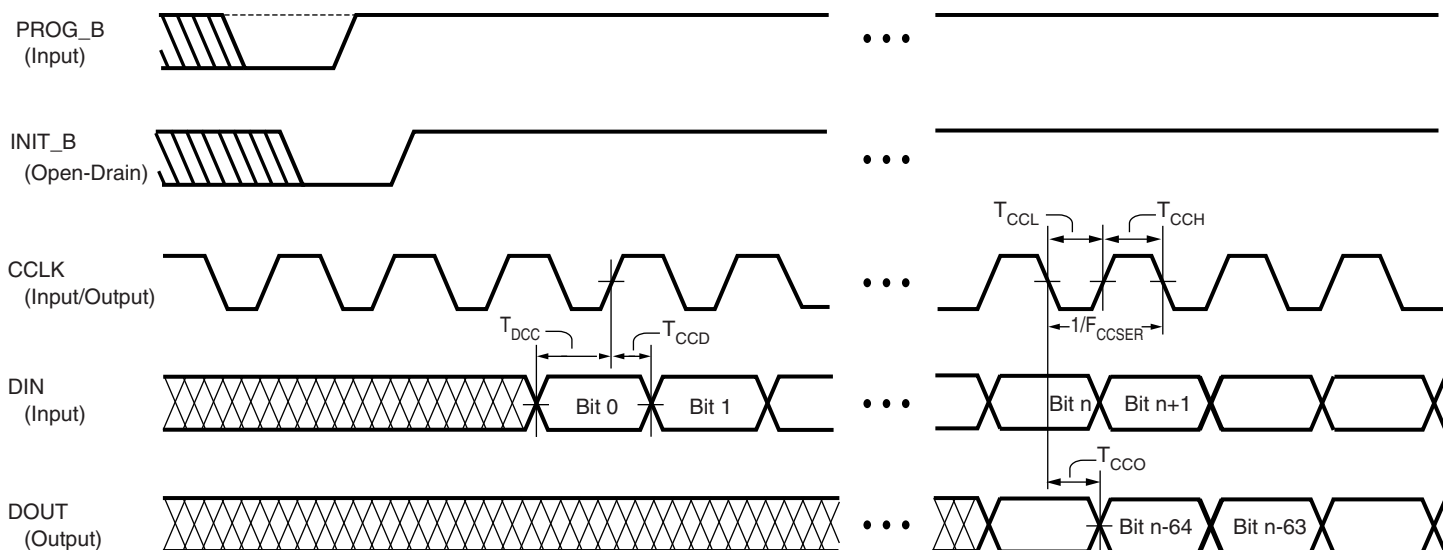
- The numbers in this table are based on the operating conditions set forth in [Table 32](#) and [Table 58](#).
- DLL specifications apply when any of the DLL outputs (CLK0, CLK90, CLK180, CLK270, CLK2X, CLK2X180, or CLKDV) are in use.
- Only mask revision 'E' and later devices (see [Mask and Fab Revisions, page 58](#)) and all revisions of the XC3S50 and the XC3S1000 support DLL feedback using the CLK2X output. For all other Spartan-3 devices, use feedback from the CLK0 output (instead of the CLK2X output) and set the CLK_FEEDBACK attribute to 1X.
- Indicates the maximum amount of output jitter that the DCM adds to the jitter on the CLKIN input.
- This specification only applies if the attribute DUTY_CYCLE_CORRECTION = TRUE.

Digital Frequency Synthesizer (DFS)
Table 60: Recommended Operating Conditions for the DFS

Symbol		Description	Frequency Mode	Speed Grade				Units
				-5		-4		
				Min	Max	Min	Max	
Input Frequency Ranges ⁽²⁾								
F _{CLKIN}	CLKIN_FREQ_FX	Frequency for the CLKIN input	All	1	280	1	280	MHz
Input Clock Jitter Tolerance ⁽³⁾								
CLKIN_CYC_JITT_FX_LF		Cycle-to-cycle jitter at the CLKIN input	Low	—	±300	—	±300	ps
CLKIN_CYC_JITT_FX_HF			High	—	±150	—	±150	ps
CLKIN_PER_JITT_FX		Period jitter at the CLKIN input	All	—	±1	—	±1	ns

Notes:

- DFS specifications apply when either of the DFS outputs (CLKFX or CLKFX180) are used.
- If both DFS and DLL outputs are used on the same DCM, follow the more restrictive CLKIN_FREQ_DLL specifications in [Table 58](#).
- CLKIN input jitter beyond these limits may cause the DCM to lose lock.



DS099-3_04_071604

Figure 37: Waveforms for Master and Slave Serial Configuration

Table 66: Timing for the Master and Slave Serial Configuration Modes

Symbol	Description	Slave/ Master	All Speed Grades		Units	
			Min	Max		
Clock-to-Output Times						
T _{CCO}	The time from the falling transition on the CCLK pin to data appearing at the DOUT pin	Both	1.5	12.0	ns	
Setup Times						
T _{DCC}	The time from the setup of data at the DIN pin to the rising transition at the CCLK pin	Both	10.0	—	ns	
Hold Times						
T _{CCD}	The time from the rising transition at the CCLK pin to the point when data is last held at the DIN pin	Both	0	—	ns	
Clock Timing						
T _{CCH}	CCLK input pin High pulse width		Slave	5.0	∞	ns
T _{CCL}	CCLK input pin Low pulse width			5.0	∞	ns
F _{CCSER}	Frequency of the clock signal at the CCLK input pin	No bitstream compression		0	66 ⁽²⁾	MHz
		With bitstream compression		0	20	MHz
		During STARTUP phase		0	50	MHz
ΔF _{CCSER}	Variation from the CCLK output frequency set using the ConfigRate BitGen option		Master	–50%	+50%	—

Notes:

1. The numbers in this table are based on the operating conditions set forth in Table 32.
2. For serial configuration with a daisy-chain of multiple FPGAs, the maximum limit is 25 MHz.

Table 72: Dual-Purpose Configuration Pins for Parallel (SelectMAP) Configuration Modes (Cont'd)

Pin Name	Direction	Description								
BUSY	Output	Configuration Data Rate Control for Parallel Mode: In the Slave and Master Parallel modes, BUSY throttles the rate at which configuration data is loaded. BUSY is only necessary if CCLK operates at greater than 50 MHz. Ignore BUSY for frequencies of 50 MHz and below. When BUSY is Low, the FPGA accepts the next configuration data byte on the next rising CCLK edge for which CS_B and RDWR_B are Low. When BUSY is High, the FPGA ignores the next configuration data byte. The next configuration data value must be held or reloaded until the next rising CCLK edge when BUSY is Low. When CS_B is High, BUSY is in a high impedance state. <table><thead><tr><th>BUSY</th><th>Function</th></tr></thead><tbody><tr><td>0</td><td>The FPGA is ready to accept the next configuration data byte.</td></tr><tr><td>1</td><td>The FPGA is busy processing the current configuration data byte and is not ready to accept the next byte.</td></tr><tr><td>Hi-Z</td><td>If CS_B is High, then BUSY is high impedance.</td></tr></tbody></table> This signal is located in Bank 4 and its output voltage is determined by VCCO_4. The BitGen option Persist permits this pin to retain its configuration function in the User mode.	BUSY	Function	0	The FPGA is ready to accept the next configuration data byte.	1	The FPGA is busy processing the current configuration data byte and is not ready to accept the next byte.	Hi-Z	If CS_B is High, then BUSY is high impedance.
BUSY	Function									
0	The FPGA is ready to accept the next configuration data byte.									
1	The FPGA is busy processing the current configuration data byte and is not ready to accept the next byte.									
Hi-Z	If CS_B is High, then BUSY is high impedance.									
INIT_B	Bidirectional (open-drain)	Initializing Configuration Memory/Configuration Error (active-Low): See description under Serial Configuration Modes, page 112.								

JTAG Configuration Mode

In the JTAG configuration mode all dual-purpose configuration pins are unused and behave exactly like user-I/O pins, as shown in [Table 79](#). See [Table 75](#) for Mode Select pin settings required for JTAG mode.

Dual-Purpose Pin I/O Standard During Configuration

During configuration, the dual-purpose pins default to CMOS input and output levels for the associated VCCO voltage supply pins. For example, in the Parallel configuration modes, both VCCO_4 and VCCO_5 are required. If connected to +2.5V, then the associated pins conform to the LVCMOS25 I/O standard. If connected to +3.3V, then the pins drive LVCMOS output levels and accept either LVTTL or LVCMOS input levels.

Dual-Purpose Pin Behavior After Configuration

After the configuration process completes, these pins, if they were borrowed during configuration, become user-I/O pins available to the application. If a dual-purpose configuration pin is not used during the configuration process—*i.e.*, the parallel configuration pins when using serial mode—then the pin behaves exactly like a general-purpose I/O. See [I/O Type: Unrestricted, General-purpose I/O Pins](#) section.

DCI: User I/O or Digitally Controlled Impedance Resistor Reference Input

These pins are individual user-I/O pins unless one of the I/O standards used in the bank requires the Digitally Controlled Impedance (DCI) feature. If DCI is used, then 1% precision resistors connected to the VRP_# and VRN_# pins match the impedance on the input or output buffers of the I/O standards that use DCI within the bank. The '#' character in the pin name indicates the associated I/O bank and is an integer, 0 through 7.

There are two DCI pins per I/O bank, except in the CP132 and TQ144 packages, which do not have any DCI inputs for Bank 5.

VRP and VRN Impedance Resistor Reference Inputs

The 1% precision impedance-matching resistor attached to the VRP_# pin controls the pull-up impedance of PMOS transistor in the input or output buffer. Consequently, the VRP_# pin must connect to ground. The 'P' character in "VRP" indicates that this pin controls the I/O buffer's PMOS transistor impedance. The VRP_# pin is used for both single and split termination.

Table 87: VQ100 Package Pinout (Cont'd)

Bank	XC3S50 XC3S200 Pin Name	VQ100 Pin Number	Type
6	IO_L40P_6/VREF_6	P13	VREF
6	VCCO_6	P19	VCCO
7	IO_L01N_7/VRP_7	P2	DCI
7	IO_L01P_7/VRN_7	P1	DCI
7	IO_L21N_7	P5	I/O
7	IO_L21P_7	P4	I/O
7	IO_L23N_7	P9	I/O
7	IO_L23P_7	P8	I/O
7	IO_L40N_7/VREF_7	P12	VREF
7	IO_L40P_7	P11	I/O
7	VCCO_7	P6	VCCO
N/A	GND	P3	GND
N/A	GND	P10	GND
N/A	GND	P20	GND
N/A	GND	P29	GND
N/A	GND	P41	GND
N/A	GND	P56	GND
N/A	GND	P66	GND
N/A	GND	P73	GND
N/A	GND	P82	GND
N/A	GND	P95	GND
N/A	VCCAUX	P7	VCCAUX
N/A	VCCAUX	P33	VCCAUX
N/A	VCCAUX	P58	VCCAUX
N/A	VCCAUX	P84	VCCAUX
N/A	VCCINT	P18	VCCINT
N/A	VCCINT	P45	VCCINT
N/A	VCCINT	P69	VCCINT
N/A	VCCINT	P93	VCCINT
VCCAUX	CCLK	P52	CONFIG
VCCAUX	DONE	P51	CONFIG
VCCAUX	HSWAP_EN	P98	CONFIG
VCCAUX	M0	P25	CONFIG
VCCAUX	M1	P24	CONFIG
VCCAUX	M2	P26	CONFIG
VCCAUX	PROG_B	P99	CONFIG
VCCAUX	TCK	P77	JTAG
VCCAUX	TDI	P100	JTAG

Table 91: TQ144 Package Pinout (Cont'd)

Bank	XC3S50, XC3S200, XC3S400 Pin Name	TQ144 Pin Number	Type
6,7	VCCO_LEFT	P34	VCCO
6,7	VCCO_LEFT	P3	VCCO
N/A	GND	P136	GND
N/A	GND	P139	GND
N/A	GND	P114	GND
N/A	GND	P117	GND
N/A	GND	P94	GND
N/A	GND	P101	GND
N/A	GND	P81	GND
N/A	GND	P88	GND
N/A	GND	P64	GND
N/A	GND	P67	GND
N/A	GND	P42	GND
N/A	GND	P45	GND
N/A	GND	P22	GND
N/A	GND	P29	GND
N/A	GND	P9	GND
N/A	GND	P16	GND
N/A	VCCAUX	P134	VCCAUX
N/A	VCCAUX	P120	VCCAUX
N/A	VCCAUX	P62	VCCAUX
N/A	VCCAUX	P48	VCCAUX
N/A	VCCINT	P133	VCCINT
N/A	VCCINT	P121	VCCINT
N/A	VCCINT	P61	VCCINT
N/A	VCCINT	P49	VCCINT
VCCAUX	CCLK	P72	CONFIG
VCCAUX	DONE	P71	CONFIG
VCCAUX	HSWAP_EN	P142	CONFIG
VCCAUX	M0	P38	CONFIG
VCCAUX	M1	P37	CONFIG
VCCAUX	M2	P39	CONFIG
VCCAUX	PROG_B	P143	CONFIG
VCCAUX	TCK	P110	JTAG
VCCAUX	TDI	P144	JTAG
VCCAUX	TDO	P109	JTAG
VCCAUX	TMS	P111	JTAG

ds099-3 16 121103

156	I/O: Unrestricted, general-purpose user I/O	12	DUAL: Configuration pin, then possible user I/O	29	VREF: User I/O or input voltage reference for bank
16	DCI: User I/O or reference resistor input for bank	8	GCLK: User I/O or global clock buffer input	28	VCCO: Output voltage supply for bank
7	CONFIG: Dedicated configuration pins	4	JTAG: Dedicated JTAG port pins	12	VCCINT: Internal core voltage supply (+1.2V)
0	N.C.: No unconnected pins in this package	40	GND: Ground	8	VCCAUX: Auxiliary voltage supply (+2.5V)

FG456: 456-lead Fine-pitch Ball Grid Array

The 456-lead fine-pitch ball grid array package, FG456, supports four different Spartan-3 devices, including the XC3S400, the XC3S1000, the XC3S1500, and the XC3S2000. The footprints for the XC3S1000, the XC3S1500, and the XC3S2000 are identical, as shown in [Table 100](#) and [Figure 51](#). The XC3S400, however, has fewer I/O pins which consequently results in 69 unconnected pins on the FG456 package, labeled as “N.C.” In [Table 100](#) and [Figure 51](#), these unconnected pins are indicated with a black diamond symbol (◆).

All the package pins appear in [Table 100](#) and are sorted by bank number, then by pin name. Pairs of pins that form a differential I/O pair appear together in the table. The table also shows the pin number for each pin and the pin type, as defined earlier.

If there is a difference between the XC3S400 pinout and the pinout for the XC3S1000, the XC3S1500, or the XC3S2000, then that difference is highlighted in [Table 100](#). If the table entry is shaded grey, then there is an unconnected pin on the XC3S400 that maps to a user-I/O pin on the XC3S1000, XC3S1500, and XC3S2000. If the table entry is shaded tan, then the unconnected pin on the XC3S400 maps to a VREF-type pin on the XC3S1000, the XC3S1500, or the XC3S2000. If the other VREF pins in the bank all connect to a voltage reference to support a special I/O standard, then also connect the N.C. pin on the XC3S400 to the same VREF voltage. This provides maximum flexibility as you could potentially migrate a design from the XC3S400 device to an XC3S1000, an XC3S1500, or an XC3S2000 FPGA without changing the printed circuit board.

An electronic version of this package pinout table and footprint diagram is available for download from the Xilinx website at http://www.xilinx.com/support/documentation/data_sheets/s3_pin.zip.

Pinout Table

Table 100: FG456 Package Pinout

Bank	3S400 Pin Name	3S1000, 3S1500, 3S2000 Pin Name	FG456 Pin Number	Type
0	IO	IO	A10	I/O
0	IO	IO	D9	I/O
0	IO	IO	D10	I/O
0	IO	IO	F6	I/O
0	IO/VREF_0	IO/VREF_0	A3	VREF
0	IO/VREF_0	IO/VREF_0	C7	VREF
0	N.C. (◆)	IO/VREF_0	E5	VREF
0	IO/VREF_0	IO/VREF_0	F7	VREF
0	IO_L01N_0/VRP_0	IO_L01N_0/VRP_0	B4	DCI
0	IO_L01P_0/VRN_0	IO_L01P_0/VRN_0	A4	DCI
0	IO_L06N_0	IO_L06N_0	D5	I/O
0	IO_L06P_0	IO_L06P_0	C5	I/O
0	IO_L09N_0	IO_L09N_0	B5	I/O
0	IO_L09P_0	IO_L09P_0	A5	I/O
0	IO_L10N_0	IO_L10N_0	E6	I/O
0	IO_L10P_0	IO_L10P_0	D6	I/O
0	IO_L15N_0	IO_L15N_0	C6	I/O
0	IO_L15P_0	IO_L15P_0	B6	I/O
0	IO_L16N_0	IO_L16N_0	E7	I/O
0	IO_L16P_0	IO_L16P_0	D7	I/O
0	N.C. (◆)	IO_L19N_0	B7	I/O
0	N.C. (◆)	IO_L19P_0	A7	I/O

Table 100: FG456 Package Pinout (Cont'd)

Bank	3S400 Pin Name	3S1000, 3S1500, 3S2000 Pin Name	FG456 Pin Number	Type
N/A	GND	GND	P13	GND
N/A	GND	GND	P14	GND
N/A	GND	GND	P20	GND
N/A	GND	GND	Y9	GND
N/A	GND	GND	Y14	GND
N/A	VCCAUX	VCCAUX	A6	VCCAUX
N/A	VCCAUX	VCCAUX	A17	VCCAUX
N/A	VCCAUX	VCCAUX	AB6	VCCAUX
N/A	VCCAUX	VCCAUX	AB17	VCCAUX
N/A	VCCAUX	VCCAUX	F1	VCCAUX
N/A	VCCAUX	VCCAUX	F22	VCCAUX
N/A	VCCAUX	VCCAUX	U1	VCCAUX
N/A	VCCAUX	VCCAUX	U22	VCCAUX
N/A	VCCINT	VCCINT	G7	VCCINT
N/A	VCCINT	VCCINT	G8	VCCINT
N/A	VCCINT	VCCINT	G15	VCCINT
N/A	VCCINT	VCCINT	G16	VCCINT
N/A	VCCINT	VCCINT	H7	VCCINT
N/A	VCCINT	VCCINT	H16	VCCINT
N/A	VCCINT	VCCINT	R7	VCCINT
N/A	VCCINT	VCCINT	R16	VCCINT
N/A	VCCINT	VCCINT	T7	VCCINT
N/A	VCCINT	VCCINT	T8	VCCINT
N/A	VCCINT	VCCINT	T15	VCCINT
N/A	VCCINT	VCCINT	T16	VCCINT
VCCAUX	CCLK	CCLK	AA22	CONFIG
VCCAUX	DONE	DONE	AB21	CONFIG
VCCAUX	HSWAP_EN	HSWAP_EN	B3	CONFIG
VCCAUX	M0	M0	AB2	CONFIG
VCCAUX	M1	M1	AA1	CONFIG
VCCAUX	M2	M2	AB3	CONFIG
VCCAUX	PROG_B	PROG_B	A2	CONFIG
VCCAUX	TCK	TCK	A21	JTAG
VCCAUX	TDI	TDI	B1	JTAG
VCCAUX	TDO	TDO	B22	JTAG
VCCAUX	TMS	TMS	A20	JTAG

Table 107: FG900 Package Pinout (Cont'd)

Bank	XC3S2000 Pin Name	XC3S4000, XC3S5000 Pin Name	FG900 Pin Number	Type
N/A	GND	GND	R17	GND
N/A	GND	GND	T17	GND
N/A	GND	GND	U17	GND
N/A	GND	GND	V17	GND
N/A	GND	GND	AC17	GND
N/A	GND	GND	AF17	GND
N/A	GND	GND	AK17	GND
N/A	GND	GND	N18	GND
N/A	GND	GND	P18	GND
N/A	GND	GND	R18	GND
N/A	GND	GND	T18	GND
N/A	GND	GND	U18	GND
N/A	GND	GND	V18	GND
N/A	GND	GND	R19	GND
N/A	GND	GND	T19	GND
N/A	GND	GND	A21	GND
N/A	GND	GND	E21	GND
N/A	GND	GND	H21	GND
N/A	GND	GND	AC21	GND
N/A	GND	GND	AF21	GND
N/A	GND	GND	AK21	GND
N/A	GND	GND	K23	GND
N/A	GND	GND	P23	GND
N/A	GND	GND	U23	GND
N/A	GND	GND	AA23	GND
N/A	GND	GND	A25	GND
N/A	GND	GND	AK25	GND
N/A	GND	GND	E26	GND
N/A	GND	GND	K26	GND
N/A	GND	GND	P26	GND
N/A	GND	GND	U26	GND
N/A	GND	GND	AA26	GND
N/A	GND	GND	AF26	GND
N/A	GND	GND	A29	GND
N/A	GND	GND	B29	GND
N/A	GND	GND	AJ29	GND
N/A	GND	GND	AK29	GND
N/A	GND	GND	A30	GND
N/A	GND	GND	B30	GND
N/A	GND	GND	F30	GND

FG900 Footprint

Left Half of FG900 Package (Top View)

XC3S2000

(565 max. user I/O)

481 I/O: Unrestricted, general-purpose user I/O

48 VREF: User I/O or input voltage reference for bank

68 N.C.: Unconnected pins for XC3S2000 (◆)

XC3S4000, XC3S5000

(633 max user I/O)

549 I/O: Unrestricted, general-purpose user I/O

48 VREF: User I/O or input voltage reference for bank

0 N.C.: No unconnected pins in this package

All devices

12 DUAL: Configuration pin, then possible user I/O

8 GCLK: User I/O or global clock buffer input

16 DCI: User I/O or reference resistor input for bank

7 CONFIG: Dedicated configuration pins

4 JTAG: Dedicated JTAG port pins

32 VCCINT: Internal core voltage supply (+1.2V)

80 VCCO: Output voltage supply for bank

24 VCCAUX: Auxiliary voltage supply (+2.5V)

120 GND: Ground

Bank 0														
1	2	3	4	5	6	7	8	9	10	11	12	13	14	15
A	GND	GND	HSWAP_EN	I/O L01P_0 VRN_0	I/O L02P_0	GND	I/O L35P_0	I/O L09P_0	I/O L38P_0	GND	I/O L17P_0	I/O L22P_0	I/O L25P_0	GND
B	GND	GND	PROG_B	I/O L01N_0 VRP_0	I/O L02N_0	I/O L04P_0	I/O L35N_0	I/O L09N_0	I/O L38N_0	I/O L12P_0	I/O L17N_0	I/O L22N_0	I/O L25N_0	I/O L28P_0
C	I/O L01N_7 VRP_7	I/O L01P_7 VRN_7	TDI	I/O VREF_0	VCCO_0	I/O L04N_0	I/O L06P_0	I/O L08P_0	VCCO_0	I/O L12N_0	I/O L16P_0	I/O L21P_0	VCCO_0	I/O L28N_0
D	I/O L03N_7 VRP_7	I/O L03P_7	I/O L02N_7	I/O L02P_7	I/O L03N_0	VCCAUX	I/O L06N_0	I/O L08N_0	I/O L37P_0	VCCAUX	I/O L16N_0	I/O L21N_0	I/O	VCCAUX
E	I/O L04N_7	I/O L04P_7	VCCO_7	I/O L05P_7	GND	I/O L03P_0	VCCO_0	I/O L07P_0	I/O L37N_0	GND	I/O L15P_0	I/O L20P_0	I/O L24P_0	GND
F	GND	I/O L06N_7	I/O L06P_7	VCCAUX	I/O L05N_7	I/O L05N_0	I/O L05P_0 VREF_0	I/O L07N_0	I/O VREF_0	I/O L11P_0	I/O L15N_0	I/O L20N_0	I/O L24N_0	I/O L27P_0
G	I/O L08N_7	I/O L08P_7	I/O L07N_7	I/O VCCO_7	I/O L09P_7	I/O L36N_0	I/O L09P_0	I/O	VCCO_0	I/O L11N_0	I/O L14P_0	I/O L19P_0	VCCO_0	I/O L27N_0
H	I/O L13N_7	I/O L13P_7	I/O L11N_7	I/O L11P_7	I/O L10N_7	I/O L10P_7 VREF_7	I/O L09N_7	I/O L36P_0	I/O L10P_0	GND	I/O L14N_0	I/O L19N_0	I/O L23P_0	GND
J	I/O L15N_7	I/O L15P_7	VCCO_7	I/O L14N_7	I/O L14P_7	I/O	VCCO_0	I/O L16P_7 VREF_7	I/O L10N_0	I/O L13N_0	VCCO_0	I/O L18P_0	I/O L23N_0	I/O L26P_0 VREF_0
K	GND	I/O L19N_7 VRP_7	I/O L19P_7	VCCAUX	GND	I/O L17N_7	I/O L17P_7	GND	I/O L16N_7	I/O L20P_7	I/O L13P_0	I/O L18N_0	I/O	I/O L26N_0
L	I/O L24N_7	I/O L24P_7	I/O L23N_7	I/O L23P_7	I/O L22N_7	I/O L22P_7	I/O L21N_7	I/O L21P_7	VCCO_7	I/O L20N_7	VCCINT	VCCO_0	VCCO_0	VCCO_0
M	I/O L27N_7	I/O L27P_7 VREF_7	I/O L26N_7	I/O L26P_7	I/O L49P_7	I/O L25N_7	I/O L25P_7	I/O L46P_7	I/O L46N_7	I/O L28P_7	VCCO_7	VCCINT	VCCINT	VCCINT
N	I/O L31N_7	I/O L31P_7	VCCO_7	I/O L50N_7	I/O L50P_7	I/O L49N_7	VCCO_7	I/O L29P_7	I/O L29N_7	I/O L28N_7	VCCO_7	VCCINT	GND	GND
P	GND	I/O L34N_7	I/O L34P_7	VCCAUX	GND	I/O L33N_7	I/O L33P_7	GND	I/O L32N_7	I/O L32P_7	VCCO_7	VCCINT	GND	GND
R	I/O L40N_7 VRP_7	I/O L40P_7	I/O L39P_7	I/O L39P_7	I/O L38N_7	I/O L38P_7	I/O L37N_7	I/O L37P_7 VREF_7	I/O L35N_7	I/O L35P_7	VCCINT	GND	GND	GND
T	I/O L40P_6 VRP_6	I/O L40N_6	I/O L39P_6	I/O L39N_6	I/O L38P_6	I/O L38N_6	I/O L52P_6	I/O L52N_6	I/O L37P_6	I/O L37N_6	VCCINT	GND	GND	GND
U	GND	I/O L36P_6	I/O L36N_6	VCCAUX	GND	I/O L35P_6	I/O L35N_6	GND	I/O L34P_6	I/O L34N_6 VREF_6	VCCO_6	VCCINT	GND	GND
V	I/O L33P_6	I/O L33N_6	VCCO_6	I/O L32P_6	I/O L32N_6	I/O L31P_6	VCCO_6	I/O L30P_6	I/O L30N_6	I/O L29P_6	VCCO_6	VCCINT	GND	GND
W	I/O L28P_6	I/O L28N_6	I/O L27P_6	I/O L27N_6	I/O L31N_6	I/O L26P_6	I/O L26N_6	I/O L25P_6	I/O L25N_6	I/O L29N_6	VCCO_6	VCCINT	VCCINT	VCCINT
Y	I/O L24P_6	I/O L24N_6 VREF_6	I/O L45P_6	I/O L45N_6	I/O L22P_6	I/O L22N_6	I/O L21P_6	I/O L21N_6	VCCO_6	I/O L20P_6	VCCINT	VCCO_5	VCCO_5	VCCO_5
A	GND	I/O L19P_6	I/O L19N_6	VCCAUX	GND	I/O L17P_6 VREF_6	I/O L17N_6	GND	I/O L16P_6	I/O L20N_6	I/O	I/O L22P_5	I/O L22N_5	I/O L26P_5
B	I/O L15P_6	I/O L15N_6	VCCO_6	I/O L14P_6	I/O L14N_6	I/O	VCCO_6	I/O L16N_6	I/O L08P_5	I/O	VCCO_5	I/O L17N_5	I/O L23P_5	I/O L26N_5
C	I/O L13P_6 VRP_6	I/O L13N_6	I/O L11P_6	I/O L11N_6	I/O L10P_6	I/O L10N_6	I/O L09P_6	I/O L36P_5	I/O L08N_5	GND	I/O L17P_5	I/O L18P_5	I/O L23N_5	GND
D	I/O L08P_6	I/O L08N_6	I/O L07P_6	I/O L07N_6	VCCO_6	I/O L09N_6 VREF_6	I/O L05P_5	I/O L36N_5	VCCO_5	I/O L13P_5	I/O L13N_5	I/O L18N_5	VCCO_5	I/O L30P_5
A	GND	I/O L06P_6	I/O L06N_6	VCCAUX	I/O L05P_6	I/O	I/O L05N_5	I/O L37P_5	I/O L11P_5	I/O L11N_5 VREF_5	I/O L14P_5	I/O L19P_5 VREF_5	I/O L27P_5	I/O L27N_5 VREF_5
F	I/O L04P_6	I/O L04N_6	VCCO_6	I/O L05N_6	GND	I/O L03N_5	VCCO_5	I/O L37N_5	I/O L09P_5	GND	I/O L14N_5	I/O L19N_5	I/O L24P_5	GND
G	I/O L03P_6	I/O L03N_6 VRP_6	I/O L02P_6	I/O L02N_6	I/O L03P_5	VCCAUX	I/O L06P_5	I/O L38P_5	I/O L09N_5	VCCAUX	I/O L15P_5	I/O L20P_5	I/O L24N_5	VCCAUX
H	I/O L01P_6 VRN_6	I/O L01N_6 VRP_6	M1	I/O VREF_5	VCCO_5	I/O L04P_5	I/O L06N_5	I/O L38N_5	VCCO_5	I/O L12P_5	I/O L15N_5	I/O L20N_5	VCCO_5	I/O L28P_5 D7
J	GND	GND	M0	I/O L01P_5 CS_B	I/O L02P_5	I/O L04N_5	I/O L07P_5	I/O L35P_5 VRN_5	I/O L12N_5	I/O L16P_5	I/O L21P_5	I/O L25P_5	I/O L28N_5 D6	I/O L32N_5 GCLK3
K	GND	GND	M2	I/O L01N_5 RDWR_B	I/O L02N_5	GND	I/O L35N_5	I/O L07N_5	I/O L10N_5 VRP_5	GND	I/O L16N_5	I/O L21N_5	I/O L25N_5	GND

Figure 55: FG900 Package Footprint (Top View)

DS099-4_13a_121103

**Right Half of FG900
Package (Top View)**

Figure 56: FG900 Package Footprint (Top View) Continued

Table 110: FG1156 Package Pinout (Cont'd)

Bank	XC3S4000 Pin Name	XC3S5000 Pin Name	FG1156 Pin Number	Type
3	IO_L48P_3	IO_L48P_3	AB24	I/O
3	N.C. (◆)	IO_L49N_3	AA26	I/O
3	N.C. (◆)	IO_L49P_3	AA25	I/O
3	IO_L50N_3	IO_L50N_3	Y25	I/O
3	IO_L50P_3	IO_L50P_3	Y24	I/O
3	N.C. (◆)	IO_L51N_3	V24	I/O
3	N.C. (◆)	IO_L51P_3	W24	I/O
3	VCCO_3	VCCO_3	AA23	VCCO
3	VCCO_3	VCCO_3	AB23	VCCO
3	VCCO_3	VCCO_3	AB29	VCCO
3	VCCO_3	VCCO_3	AB33	VCCO
3	VCCO_3	VCCO_3	AD27	VCCO
3	VCCO_3	VCCO_3	AD31	VCCO
3	VCCO_3	VCCO_3	AG28	VCCO
3	VCCO_3	VCCO_3	AG32	VCCO
3	VCCO_3	VCCO_3	AL32	VCCO
3	VCCO_3	VCCO_3	W23	VCCO
3	VCCO_3	VCCO_3	W31	VCCO
3	VCCO_3	VCCO_3	Y23	VCCO
3	VCCO_3	VCCO_3	Y27	VCCO
4	IO	IO	AD18	I/O
4	IO	IO	AD19	I/O
4	IO	IO	AD20	I/O
4	IO	IO	AD22	I/O
4	IO	IO	AE18	I/O
4	IO	IO	AE19	I/O
4	IO	IO	AE22	I/O
4	N.C. (◆)	IO	AE24	I/O
4	IO	IO	AF24	I/O
4	N.C. (◆)	IO	AF26	I/O
4	IO	IO	AG26	I/O
4	IO	IO	AG27	I/O
4	IO	IO	AJ27	I/O
4	IO	IO	AJ29	I/O
4	IO	IO	AK25	I/O
4	IO	IO	AN26	I/O
4	IO/VREF_4	IO/VREF_4	AF21	VREF
4	IO/VREF_4	IO/VREF_4	AH23	VREF
4	IO/VREF_4	IO/VREF_4	AK18	VREF
4	IO/VREF_4	IO/VREF_4	AL30	VREF

Table 110: FG1156 Package Pinout (Cont'd)

Bank	XC3S4000 Pin Name	XC3S5000 Pin Name	FG1156 Pin Number	Type
6	IO_L16N_6	IO_L16N_6	AE2	I/O
6	IO_L16P_6	IO_L16P_6	AE1	I/O
6	IO_L17N_6	IO_L17N_6	AD10	I/O
6	IO_L17P_6/VREF_6	IO_L17P_6/VREF_6	AD9	VREF
6	IO_L19N_6	IO_L19N_6	AD2	I/O
6	IO_L19P_6	IO_L19P_6	AD1	I/O
6	IO_L20N_6	IO_L20N_6	AC11	I/O
6	IO_L20P_6	IO_L20P_6	AC10	I/O
6	IO_L21N_6	IO_L21N_6	AC8	I/O
6	IO_L21P_6	IO_L21P_6	AC7	I/O
6	IO_L22N_6	IO_L22N_6	AC6	I/O
6	IO_L22P_6	IO_L22P_6	AC5	I/O
6	IO_L23N_6	IO_L23N_6	AC2	I/O
6	IO_L23P_6	IO_L23P_6	AC1	I/O
6	IO_L24N_6/VREF_6	IO_L24N_6/VREF_6	AC9	VREF
6	IO_L24P_6	IO_L24P_6	AB10	I/O
6	IO_L25N_6	IO_L25N_6	AB8	I/O
6	IO_L25P_6	IO_L25P_6	AB7	I/O
6	IO_L26N_6	IO_L26N_6	AB4	I/O
6	IO_L26P_6	IO_L26P_6	AB3	I/O
6	IO_L27N_6	IO_L27N_6	AB11	I/O
6	IO_L27P_6	IO_L27P_6	AA11	I/O
6	IO_L28N_6	IO_L28N_6	AA8	I/O
6	IO_L28P_6	IO_L28P_6	AA7	I/O
6	IO_L29N_6	IO_L29N_6	AA6	I/O
6	IO_L29P_6	IO_L29P_6	AA5	I/O
6	IO_L30N_6	IO_L30N_6	AA4	I/O
6	IO_L30P_6	IO_L30P_6	AA3	I/O
6	IO_L31N_6	IO_L31N_6	AA2	I/O
6	IO_L31P_6	IO_L31P_6	AA1	I/O
6	IO_L32N_6	IO_L32N_6	Y11	I/O
6	IO_L32P_6	IO_L32P_6	Y10	I/O
6	IO_L33N_6	IO_L33N_6	Y4	I/O
6	IO_L33P_6	IO_L33P_6	Y3	I/O
6	IO_L34N_6/VREF_6	IO_L34N_6/VREF_6	Y2	VREF
6	IO_L34P_6	IO_L34P_6	Y1	I/O
6	IO_L35N_6	IO_L35N_6	Y9	I/O
6	IO_L35P_6	IO_L35P_6	W10	I/O
6	IO_L36N_6	IO_L36N_6	W7	I/O
6	IO_L36P_6	IO_L36P_6	W6	I/O

Table 110: FG1156 Package Pinout (Cont'd)

Bank	XC3S4000 Pin Name	XC3S5000 Pin Name	FG1156 Pin Number	Type
N/A	GND	GND	AN1	GND
N/A	GND	GND	AN2	GND
N/A	GND	GND	AN33	GND
N/A	GND	GND	AN34	GND
N/A	GND	GND	AP1	GND
N/A	GND	GND	AP13	GND
N/A	GND	GND	AP16	GND
N/A	GND	GND	AP19	GND
N/A	GND	GND	AP2	GND
N/A	GND	GND	AP22	GND
N/A	GND	GND	AP26	GND
N/A	GND	GND	AP30	GND
N/A	GND	GND	AP33	GND
N/A	GND	GND	AP34	GND
N/A	GND	GND	AP5	GND
N/A	GND	GND	AP9	GND
N/A	GND	GND	B1	GND
N/A	GND	GND	B2	GND
N/A	GND	GND	B33	GND
N/A	GND	GND	B34	GND
N/A	GND	GND	C11	GND
N/A	GND	GND	C24	GND
N/A	GND	GND	C3	GND
N/A	GND	GND	C32	GND
N/A	GND	GND	E1	GND
N/A	GND	GND	E13	GND
N/A	GND	GND	E16	GND
N/A	GND	GND	E19	GND
N/A	GND	GND	E22	GND
N/A	GND	GND	E26	GND
N/A	GND	GND	E30	GND
N/A	GND	GND	E34	GND
N/A	GND	GND	E5	GND
N/A	GND	GND	E9	GND
N/A	GND	GND	G28	GND
N/A	GND	GND	G7	GND
N/A	GND	GND	J1	GND
N/A	GND	GND	J13	GND
N/A	GND	GND	J16	GND
N/A	GND	GND	J19	GND

FG1156 Footprint

Top Left Corner of FG1156 Package (Top View)

XC3S4000
(712 max. user I/O)

621 I/O: Unrestricted, general-purpose user I/O

55 VREF: User I/O or input voltage reference for bank

73 N.C.: Unconnected pins for XC3S4000 (◆)

XC3S5000
(784 max. user I/O)

692 I/O: Unrestricted, general-purpose user I/O

56 VREF: User I/O or input voltage reference for bank

1 N.C.: Unconnected pins for XC3S5000 (■)

		Bank 0																
		1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17
Bank 7	A	GND	GND	I/O L01P_0 VRN_0	I/O L02P_0	GND	I/O L05P_0 VREF_0	I/O L34P_0 ◆	I/O L36P_0	GND	I/O L38P_0	I/O L40P_0 ◆	I/O L15P_0	GND	I/O L22P_0	I/O L26P_0 VREF_0	GND	I/O L32P_0 GCLK6
	B	GND	GND	I/O L01N_0 VRP_0	I/O L02N_0	I/O L03P_0	I/O L05N_0	I/O L34N_0 ◆	I/O L36N_0	I/O	I/O L38N_0	I/O L40N_0 ◆	I/O L15N_0	VCCO_0	I/O L22N_0	I/O L26N_0	I/O L28P_0	I/O L32N_0 GCLK7
	C	I/O L01N_7 VRP_7	I/O L01P_7 VRN_7	GND	VCCO_0	I/O L03N_0	I/O L04P_0	I/O L33P_0 ◆	VCCO_0	I/O L08P_0	I/O L37P_0	GND	I/O L14P_0	I/O L17P_0	I/O L21P_0	I/O L25P_0	I/O L28N_0	I/O L31P_0 VREF_0
	D	I/O L02N_7	I/O L02P_7	VCCO_7	PROG_B	IO VREF_0	I/O L04N_0	I/O L33N_0 ◆	I/O L35P_0	I/O L08N_0	I/O L37N_0	VCCO_0	I/O L14N_0	I/O L17N_0	I/O L21N_0	I/O L25N_0	VCCO_0	I/O L31N_0
	E	GND	I/O L03N_7 VREF_7	I/O L03P_7	TDI	GND	VCCAUX	I/O L06P_0	I/O L35N_0	GND	IO VREF_0	VCCAUX	I/O L13P_0	GND	I/O L20P_0	VCCAUX	GND	I/O
	F	I/O L05N_7	I/O L05P_7	I/O L04N_7	I/O L04P_7	VCCAUX	I/O	I/O L06N_0	I/O	I/O L07P_0	I/O L10P_0	I/O L39P_0 ◆	I/O L13N_0	VCCO_0	I/O L20N_0	I/O L24P_0	I/O L27P_0	I/O L30P_0
	G	I/O	I/O	I/O L41N_7 ◆	I/O L41P_7 ◆	I/O L06N_7	I/O L06P_7	GND	VCCO_0	I/O L07N_0	I/O L10N_0	I/O L39N_0 ◆	I/O	I/O L16P_0	I/O L19P_0	I/O L24N_0	I/O L27N_0	I/O L30N_0
	H	I/O L08N_7	I/O L08P_7	VCCO_7	I/O L10P_7 VREF_7	I/O L07N_7	I/O L07P_7	VCCO_7	I/O	I/O	I/O L09P_0	VCCO_0	I/O L12P_0	I/O L16N_0	I/O L19N_0	VCCO_0	VCCAUX	I/O L29P_0
	J	GND	I/O L11N_7	I/O L11P_7	I/O L10N_7	GND	I/O L09N_7	I/O L09P_7	I/O L12P_7	I/O ◆	I/O L09N_0	I/O	I/O L12N_0	GND	IO VREF_0	I/O L23P_0	GND	I/O L29N_0
	K	I/O L16N_7	I/O L16P_7 VREF_7	I/O L15N_7	I/O L15P_7	I/O L14N_7	I/O L14P_7	I/O L13N_7	I/O L13P_7	I/O L12N_7	GND	I/O ◆	I/O L11P_0	I/O	I/O L18P_0	I/O L23N_0	I/O	I/O
	L	I/O L19N_7 VREF_7	I/O L19P_7	GND	VCCO_7	VCCAUX	I/O L44N_7 ◆	I/O L44P_7 ◆	VCCO_7	I/O L17N_7	I/O L17P_7	HSWAP_EN	I/O L11N_0	I/O	I/O L18N_0	IO VREF_0	I/O	I/O
	M	I/O L45N_7	I/O L45P_7	I/O L23N_7	I/O L23P_7	I/O L22N_7	I/O L22P_7	I/O L21N_7	I/O L21P_7	I/O L24P_7	I/O L20N_7	I/O L20P_7	VCCINT	VCCO_0	VCCO_0	VCCO_0	VCCO_0	VCCINT
	N	GND	VCCO_7	I/O L25N_7	I/O L25P_7	GND	VCCO_7	I/O L46N_7	I/O L46P_7	GND	I/O L24N_7	I/O L26P_7	VCCO_7	VCCINT	VCCINT	VCCINT	VCCINT	GND
	P	I/O L49N_7	I/O L49P_7	I/O L29N_7	I/O L29P_7	I/O L28N_7	I/O L28P_7	I/O L27N_7	I/O L27P_7 VREF_7	I/O L47N_7 ◆	I/O L47P_7 ◆	I/O L26N_7	VCCO_7	VCCINT	GND	GND	GND	GND
	R	I/O L32N_7	I/O L32P_7	I/O L31N_7	I/O L31P_7	VCCAUX	I/O L30N_7	I/O L30P_7	VCCO_7	I/O L33P_7	I/O L50N_7	I/O L50P_7	VCCO_7	VCCINT	GND	GND	GND	GND
	T	GND	I/O L35N_7	I/O L35P_7	VCCO_7	GND	I/O L34N_7	I/O L34P_7	VCCAUX	GND	I/O L33N_7	I/O L51P_7 ◆	VCCO_7	VCCINT	GND	GND	GND	GND
	U	I/O L40N_7 VREF_7	I/O L40P_7	I/O L39N_7	I/O L39P_7	I/O L38N_7	I/O L38P_7	I/O L37N_7	I/O L37P_7 VREF_7	I/O	I/O	I/O L51N_7 ◆	VCCINT	GND	GND	GND	GND	GND

Figure 57: FG1156 Package Footprint (Top View)

DS099-4_14a_072903